

FABRICATION PARAMETERS:

THICKNESS:	0.062
SILKSCREEN:	BOTH
SOLDERMASK:	BOTH
COPPER WEIGHT:	2 OZ (EXT) / 1 OZ (INT)
DESIGN TYPE:	MEK
MIN TRACE/GAP:	0.009/0.005
LAYER COUNT:	6 LAYERS

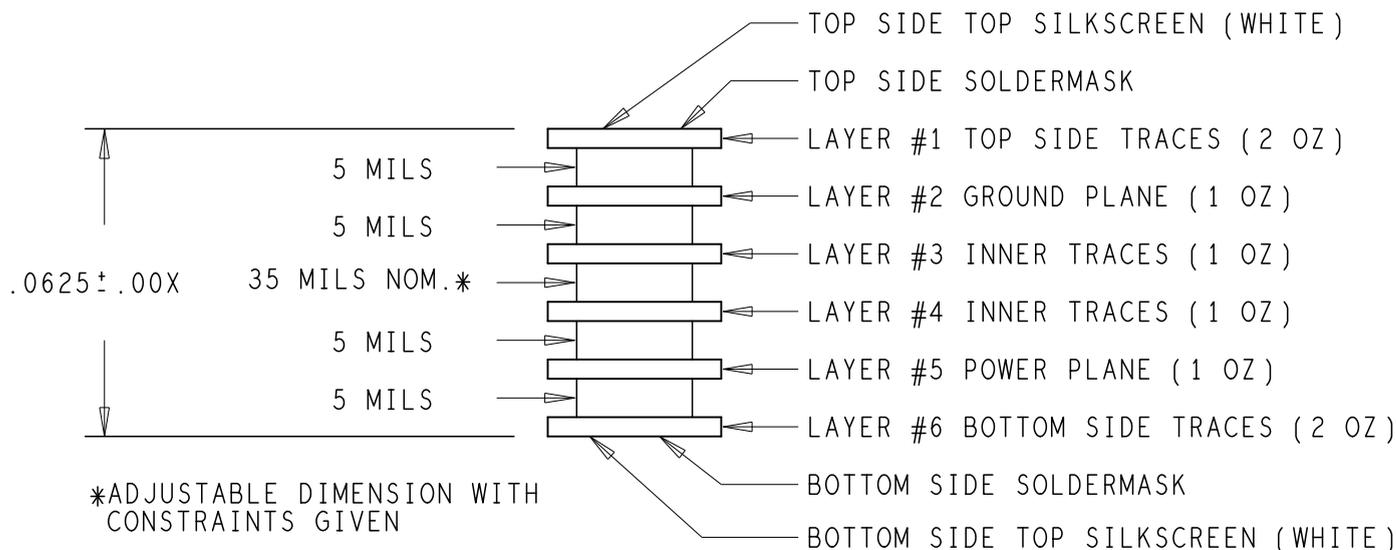
NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.
2. BASE LAMINATE: PLASTIC SHEET, LAMINATED METAL CLAD, TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 6 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3. SOLDERMASK: SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840.
4. PLATING: HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
5. FINISH: PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0005" +/- 0.0003" THICK MIN ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
6. LEGEND: IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
7. MARKINGS: BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
8. WORKMANSHIP: PCB BOARD SHALL BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
9. DOCUMENTATION: PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
10. DRILL SIZES: HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
11. PANEL BORDER: ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
12. PROCESS CHANGES: NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

DRILL CHART: TOP to BOTTOM

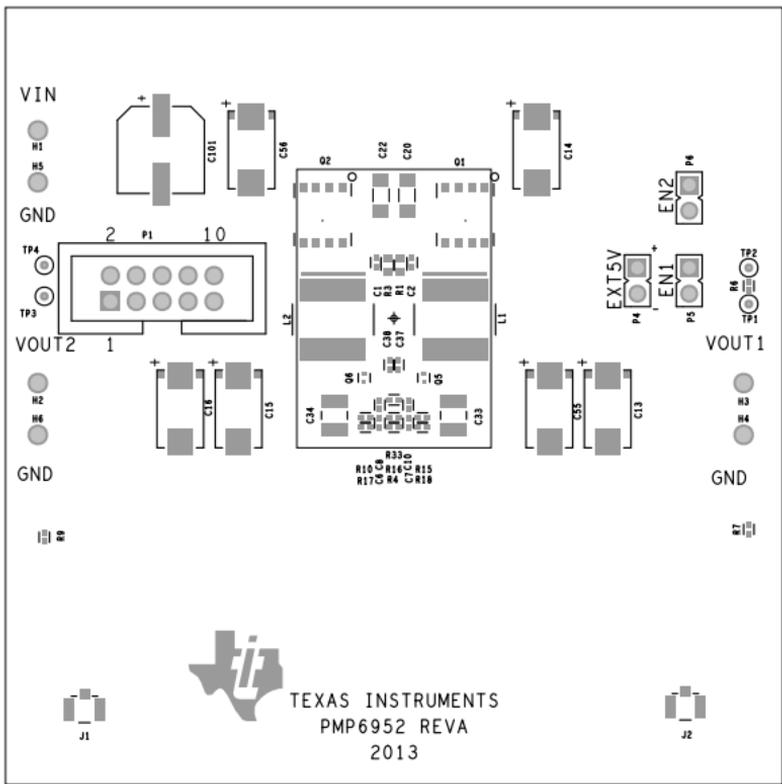
ALL UNITS ARE IN MILS

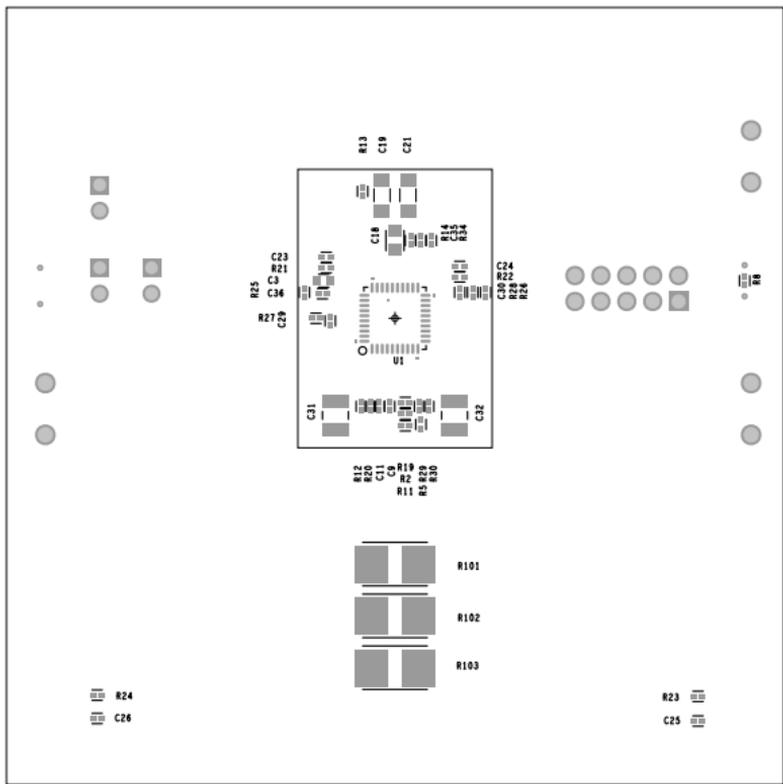
FIGURE	SIZE	TOLERANCE	PLATED	QTY
.	8.0	+3.0/-3.0	PLATED	24
⊙	10.0	+3.0/-3.0	PLATED	266
+	50.0	+3.0/-3.0	PLATED	6
f	55.0	+3.0/-3.0	PLATED	10
◇	60.0	+3.0/-3.0	PLATED	6



VIEW X-X XX

SCALE = NONE





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